

SOT864-1

plastic thermal enhanced thin shrink small outline package;
24 leads; body width 4.4 mm; lead pitch 0.65 mm; exposed
die pad

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HTSSOP24
Package type industry code	HTSSOP24
Package style descriptive code	HTSSOP (thermal enhanced thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	6-12-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.7	-	7.8	7.9	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A ₂	package height	0.8	-	0.9	0.95	mm
n ₂	actual quantity of termination	-	-	24	-	

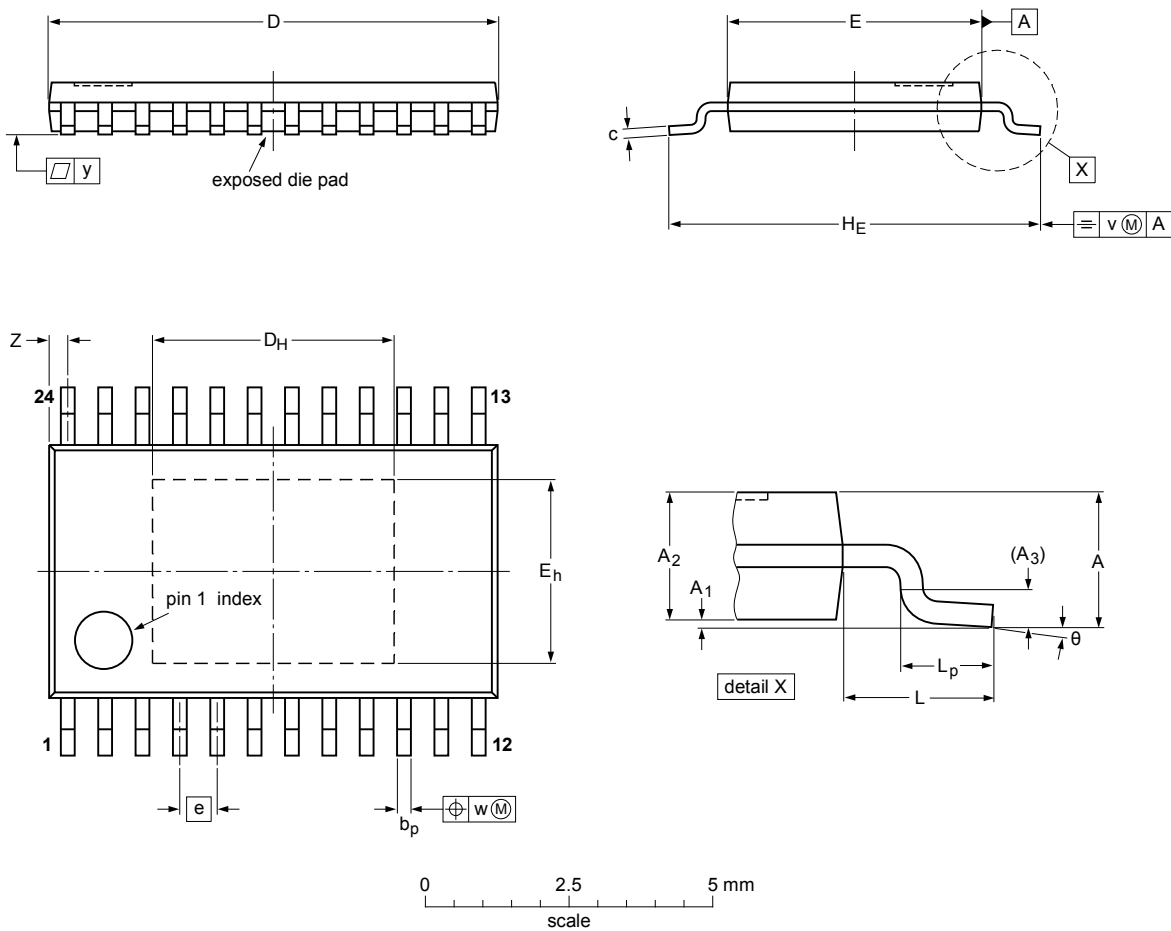


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2. Package outline

HTSSOP24: plastic thermal enhanced thin shrink small outline package; 24 leads; body width 4.4 mm; lead pitch 0.65 mm; exposed die pad

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	D _h	E ⁽²⁾	E _h	e	H _E	L	L _p	v	w	y	Z	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.3 4.1	4.5 4.3	3.3 3.1	0.65	6.6 6.2	1	0.75 0.50	0.2	0.13	0.1	0.5 0.2	8° 0

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT864-1		MO-153			04-09-23 05-12-06

Fig. 1. Package outline HTSSOP24 (SOT864-1)

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3. Legal information

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